

Mg₂Si thermoelectric conversion film with reduced thermal conductivity while keeping electrical conductivity

 $\rm Mg_2Si$ film with high porosity and uniform vacancies

Overview

The development of thermoelectric conversion technology to extract electricity from waste heat is being actively pursued. Mg_2Si is a thermoelectric conversion material suitable for the use of industrial waste heat since the thermoelectric conversion efficiency achieves its maximum value at around 300°C environment.

However, the heat is often leaked due to its high thermal conductivity so the conversion efficiency is not as high as expected (cf. right formula). There is a report that the thermal conductivity was decreased by compacting Mg_2Si powder into pellet and making it porous, but since the electrical conductivity was also reduced due the grain boundary, the conversion efficiency was not increased.

This invention is about a Mg_2Si porous film that solves the above issue.

Product Application

The present porous Mg₂Si film shows the same electrical conductivity (~2 S/cm) as an ordinary Mg₂Si thin film such as sputtered film, but the thermal conductivity is reduced by 11% even with a single porous structure layer. Therefore, it is possible to realize a thermoelectric conversion device by increasing film layers with less thermal leakage in the waste heat range around 300°C.

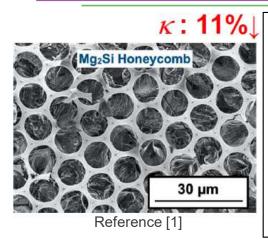
IP Data

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Polymer Honeycomb TEOS UV-O₃ Mg Vapor

Reference [1]

Low thermal conductivity by honeycomb-like highly porous film



$ZT = \frac{S^2 \sigma}{\kappa} T = \frac{ZT: \text{ figure of merit}}{\kappa} T = \frac{S^2 \sigma}{\kappa} T = \frac{ZT: \text{ figure of merit}}{\sigma: \text{ Temperature}}$

Since the Seebeck coefficient is almost constant regardless of the material form, the larger the electrical conductivity and the smaller the thermal conductivity, the energy conversion efficiency index *ZT* becomes important.

Related Works

[1] Chem. Mater. 2020, 32, 10176.

Contact

